


APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	[STRUCTURE OF A SUBSTRATE FOR A HIGH DENSITY SEMICONDUCTOR PACKAGE]		
Application Type : regular, utility Attorney Docket Number : 10517-US-PA			
Correspondence address: Customer Number: 31561 			
Continuing Data: This is a Non-Provisional of US application number 60/319,909, filed 2003-01-28 , now pending.			
Inventor Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Chung W. Family Name: Ho Residence: City of Residence: Taipei City Country of Residence: TW Address-1 of Mailing Address: 4Fl., No. 182, Sec. 1, Da-an Rd., Da-an Chiu Address-2 of Mailing Address: City of Mailing Address: Taipei City State of Mailing Address: Postal Code of Mailing Address: 106 Country of Mailing Address: TW Phone: Fax: E-mail:			
Attorney Information: practitioner(s) at Customer Number:			

31561



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